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🔍 Title: **JP2001015912A2: MULTILAYERED PRINTED WIRING BOARD AND PRODUCTION THEREOF**

🔍 Country: **JP Japan**

🔍 Kind: **A2 Document Laid open to Public inspection**

🔍 Inventor: **SEKINE KOJI;**

🔍 Assignee: **IBIDEN CO LTD**
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🔍 Published / Filed: **2001-01-19 / 1999-07-02**

🔍 Application Number: **JP1999000189208**

🔍 IPC Code: **H05K 3/46; H05K 3/00; H05K 3/28;**

🔍 Priority Number: **1999-07-02 JP1999000189208**

🔍 Abstract: **PROBLEM TO BE SOLVED:** To provide a multilayered printed wiring board and a method for producing the multilayered printed wiring board by which the arrangement density of through hole can be improved and the thickness thereof be made smaller.

SOLUTION: Interlayer resin insulation layers 24 and 38 and a core substrate 50 for upper layer are built up on a core substrate 10 for lower layer. Therefore, a plurality of core substrates 10 and 50 ensure the strength of a multilayered printed wiring board, so that the core substrate can be formed thin, and the thickness of the multilayered printed wiring board be also made small. In addition, a fine non-through hole 10a can be easily made by a laser, and a through hole 14 with a small diameter can be formed.

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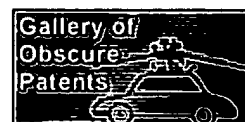
🔍 INPADOC Legal Status: **None** [Get Now: Family Legal Status Report](#)

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🔍 Other Abstract Info: **CHEMABS 134(09)124542H CHEMABS 134(09)124542H**



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